



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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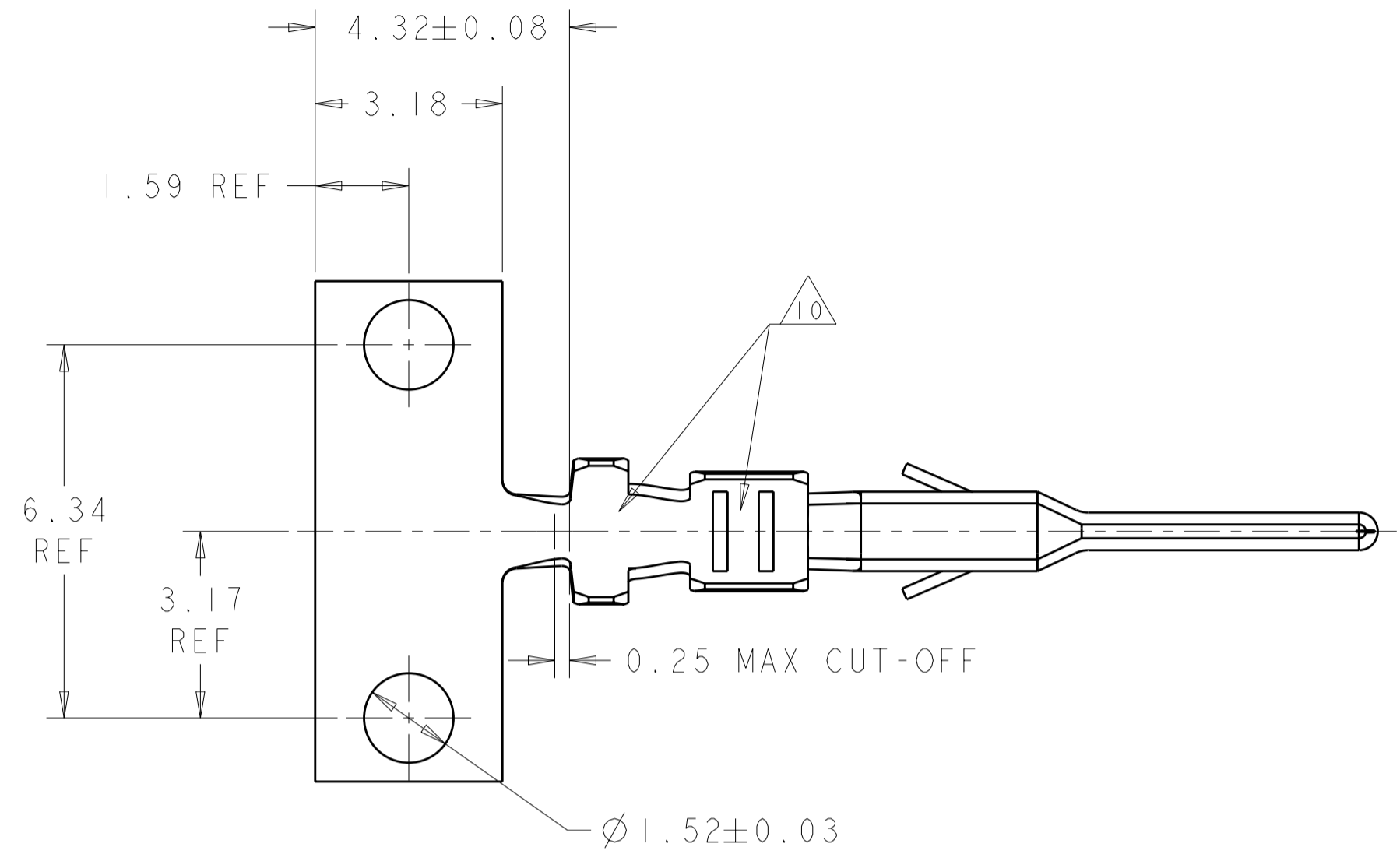
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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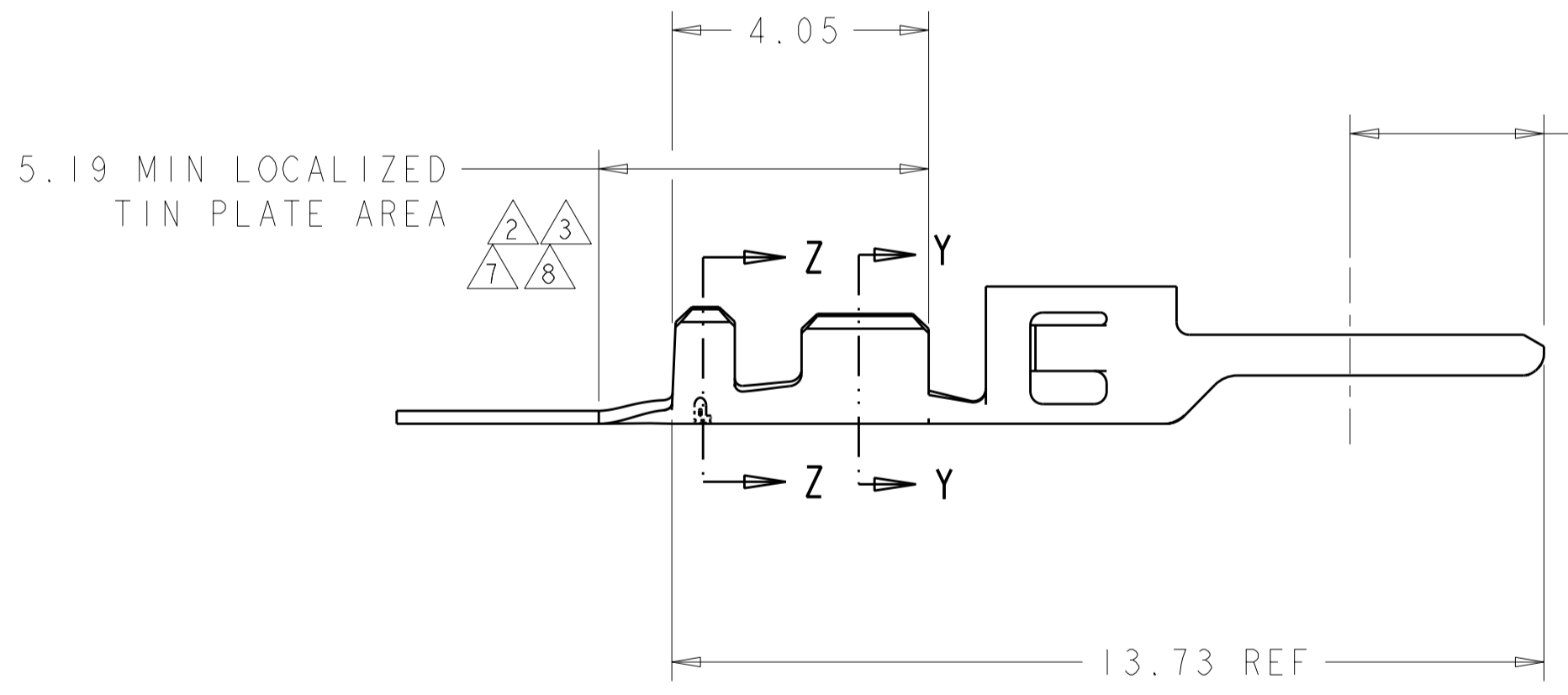


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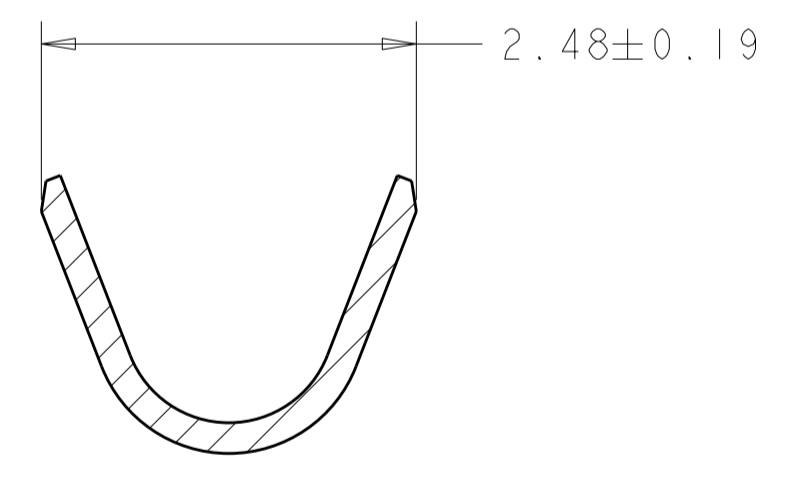
LOC	DIST	REVISIONS					
CM	00	P	LTR	DESCRIPTION	DATE	DWN	APVD
			D2	REVISED PER ECO-11-005027	15MAR2011	RK	HMR



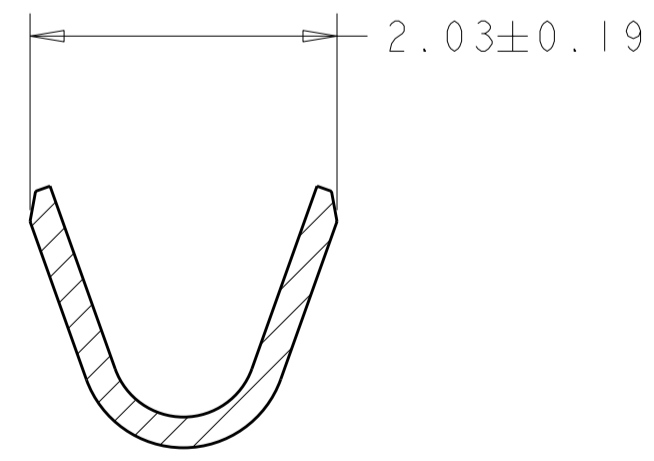
- 1 2.54 µm MIN BRIGHT TIN/LEAD ENTIRE STOCK OVER 1.27 µm MIN NICKEL ENTIRE STOCK.
- 2 0.38 µm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54 µm MIN BRIGHT TIN/LEAD IN LOCALIZED TIN/LEAD PLATE AREA, BOTH OVER 1.27 µm MIN NICKEL ON ENTIRE STOCK.
- 3 0.76 µm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54 µm MIN BRIGHT TIN/LEAD IN LOCALIZED TIN/LEAD PLATE AREA, BOTH OVER 1.27 µm MIN NICKEL ON ENTIRE STOCK.
- 4 WIRE RANGE 20-24 AWG.
- 5 INSULATION RANGE 0.89-1.52
- 6 2.54 µm MIN BRIGHT TIN ENTIRE STOCK OVER 1.27 µm MIN NICKEL ENTIRE STOCK.
- 7 0.38 µm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54 µm MIN BRIGHT TIN IN LOCALIZED TIN PLATE AREA, BOTH OVER 1.27 µm MIN NICKEL ON ENTIRE STOCK.
- 8 0.76 µm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54 µm MIN BRIGHT TIN IN LOCALIZED TIN PLATE AREA, BOTH OVER 1.27 µm MIN NICKEL ON ENTIRE STOCK.
- 9 NOTE DELETED.
- 10 TIN PLATING THICKNESS INSIDE WIRE AND INSULATION BARRELS TO BE 1.27 µm MIN.



3.00 MIN LOCALIZED GOLD PLATE AREA 2 3 7 8

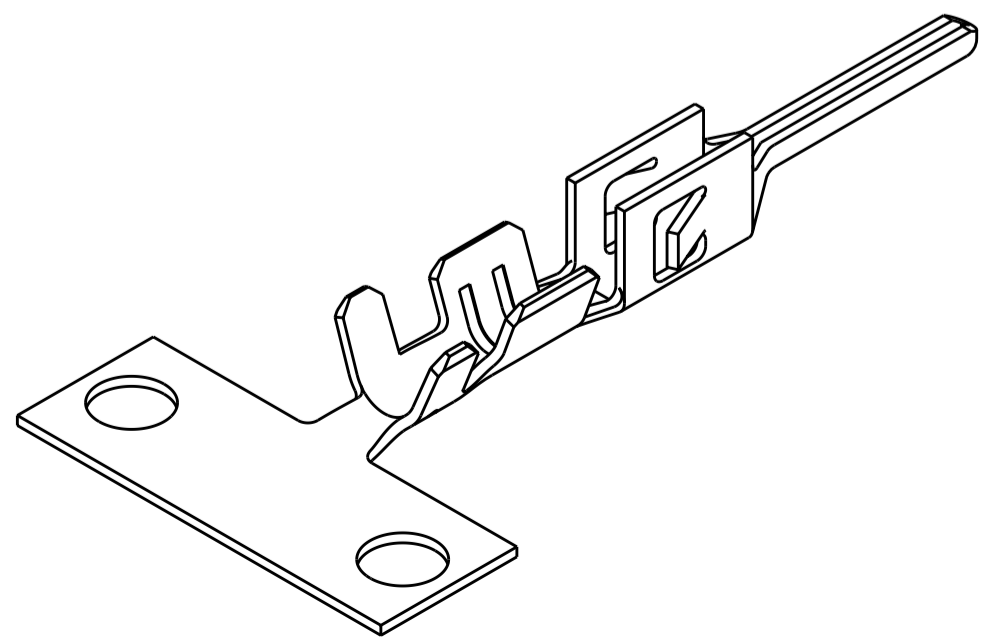


SECTION Z-Z
SCALE 20:1



SECTION Y-Y
SCALE 20:1

8	1-794608-2
7	1-794608-1
6	1-794608-0
3	794608-3
2	794608-2
1	794608-1
FINISH	PART NUMBER



THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DWN W J RUDY 29AUG2000	CHK W DAVIS 29AUG2000	APVD W DAVIS 29AUG2000	NAME
0 PLC ±	1 PLC ±	2 PLC ±0.13	3 PLC ±	4 PLC ±	PLUG CONTACT, CRIMP SNAP, 20-24 AWG, MICRO MATE-N-LOK(TM)
MATERIAL 0.20 THK BRASS		APPLICATION SPEC		SIZE CAGE CODE DRAWING NO RESTRICTED TO	
		WEIGHT		A200779C-794608	
		CUSTOMER DRAWING		SCALE 10:1 SHEET 1 OF 1 REV D2	

STE TE Connectivity